### Towards mass manufacturable Terabit transceivers for the datacentre

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# TOWARDS MASS MANUFACTURABLE **TERABIT TRANSCEIVERS FOR THE** DATACENTRE

Elad Mentovich, 6 October 2020



# BANDWIDTH DEMAND IS GROWING



- DC bandwidth demand grows exponentially
- 400G interconnects now ramping up
- 800G and 1.6T standards & MSAs in the pipeline





# MASS MARKET? MASS MANUFACTURING

## SI PHOTONICS VS. LEGACY OPTICAL TRANSCEIVER FORECAST, IN VALUE



- Transceivers are turning into a multi-Bn market
- Reaching critical mass to leverage cost savings of silicon photonics (10s M units)

(02018) www.yole.fr [ Silicon Photonics 2018 ] Sample



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# THE PACKAGING CHALLENGE



- Transceiver costs are dwarfed by assembly & packaging costs
- Cost/bit drops to enable deployment of new generation transceivers
- Existing scaling model relies on low-wage production
- Current approach reaching its limits







# THE ROAD TO TERABIT/S TRANSCEIVERS



- 100G/lane optics now ramping up
- 100G electrical ports introduced (100G SERDES)
- Speed evolution paradigm:
  - increase #lanes with existing optics
  - move to higher speed/less lanes
- 800G modules (25.6T switches) will use pluggables
  - Terabit modules will migrate to new form factors



## NEXT-GEN TRANSCEIVER WISHLIST ...addressed by MASSTART project

- Integration density
- High temperature operation
- High channel count
- Mass manufacturability
- Compatibility with advanced assembly techniques
- Low-loss/high count optical I/Os
- High-TRL laser assembly

MASSTART 300mm Silicon Photonic platform

### MASSTART SiPh TSV capability

SiPh in-plane & vertical couplers, dense WAFT fanouts

Silicon bench and assembly process with tight alignment tolerances







CEA-Leti 50 Gbaud Silicon Photonics



DUST silicon bench

## MASSTART OVERVIEW innovation across the value chain



ALMAE laser arrays



FICONTEC & Tektronix automation





TEEM WAFT

**NVIDIA** Networking integration





## **MASSTART PROTOTYPE 1** Pre-alpha 400GBASE-DR4 transceiver



- 8x 50 Gb/s PAM4 electrical interfaces
- 4x 100 Gb/s PAM4 optical lanes
- "grey" optics (no WDM)
- commercial electronics (showcase industrial relevance)





## **MASSTART PROTOTYPE 1** Pre-alpha 400GBASE-DR4 transceiver - progress



**EVB** platform layout

- Floorplans designed for QSFP-DD and OSFP form factor
- Layout for an open platform EVB designed
- DSP platform tested and modelled
- SiPh chips in fab, assembly starting Q1 2021



53 Gbaud signal @DSP



# MASSTART PROTOTYPE 2

800G 8-lane transceiver

- 8x 100 Gb/s PAM4 optical lanes
- LAN WDM optics (800 GHz)
- Commercial electronics
- EVB platform targeting pluggable/on-board optics









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# MASSTART PROTOTYPE 3

## 1.6T 16-lane transceiver

- 16x 100 Gb/s PAM4 optical lanes
- LAN WDM optics (800 GHz): 2x 8λ grid
- Focus on scalability: WAFT interface for dense optical I/Os
- EVB test platform







# CONCLUSIONS

- Silicon photonics becoming increasingly relevant for short-reach low-cost transceivers
- Dramatic reductions in assembly and packaging cost needed to meet targets
- MASSTART is developing an end-to-end solution for mass-manufacturable SiPh transceivers
- MASSTART demonstrators validate the technology in broad deployment scenarios
  - 400G pluggable transceiver
  - 800G EVB for pluggable / on-board optics
  - 1.6T EVB for on-board / co-packaged optics



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